High Speed VCSELs With Separated Quantum Wells

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Computers: past, present and future





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Cray1 1980s
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Pocket PC 2000s





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Computer I/O architecture history and I/O roadmap



Beyond 10 GHz, copper interconnects, become bandwidth limited due to frequency-dependent losses such as the skin effect in the conductors and the dielectric loss from the substrate material.

We need the optoelectronic devices with

- good performance (high-modulation bandwidth, low power consumption, high efficiency)
- manufacturing advantages (amenable to high-volume production, wafer-level testing, and ease of integration).

E. Mohammed et.al, Intel Technology Journal, V.8 N.2, 2004, pp. 115-127

Demonstrator for chip-to-chip optical interconnects on the optical PCB

Optical-fiber embedded PCB VCSEL array 250Hm Driver IC **Receiver IC** Fiber & MT ferrule Tx module embedded OPCB Rx module 90°-ben<mark>t</mark> fiber 90°-bent fiber block Guide pin Transmission test result block

90° bent optical connector

Optical interconnection platform







M. H. Cho, et. al, IEEE PHONIC. TECH. L., 17, 690 (2005).

Intracavity contacted VCSEL array







- + Bypass the current flow through mirrors ⇒ lowers the series resistance
- + Use of undoped DBR mirror
 - \Rightarrow reduce free carrier absorption
 - \Rightarrow better reflectivity
- + Co-planar contact
 - \Rightarrow suitable for flip-chip bonding

Experimental part

L-I-V characteristics









- Oxide aperture dia. : 5 µm
- Threshold current : 0.7±0.05 mA
- Threshold voltage : 1.7 V
- Slope efficiency : 0.36±0.01 W/A @ I=2mA
- Differential quantum efficiency:

28.4±0.7 %@ I=2mA

Differential resistance : 150 Ω @ I=6mA

3dB bandwidth 10 GHz at 10 mA





Axial enhancement factor

Resonance frequency

$$f_{R} = \frac{1}{2\pi} \sqrt{\eta_{i} \frac{\Gamma(\xi)_{g}}{qV_{eff}} \frac{\partial g}{\partial N} (I - I_{th})}$$

$$V_{eff} = \pi R^2 (L_{pen,top} + L_{cav} + L_{pen,bot})$$





Interactions between physical processes in LD







Vertical-cavity surface-emitting laser devices/ ed. by H.E.Li, K.Iga. (Springer series in photonics; v.6), Ch. 5

Optical field solution

For homogeneous lossless medium Maxwell's equations can be

sformed to vec. $\left(\nabla^{2} + k_{0}n_{R}^{2}\Psi\right) = 0$ $n_{RA} = \begin{cases} n_{R1} & |r| \le r_{A} \\ n_{R2} & |r| \ge r_{A} \end{cases}$ for index-guiding structure

$$E_{T}^{k,m,s} = E_{k,m,s} \exp(ik\phi) \exp(i\beta_{z}z) \begin{cases} J_{k}\left(\frac{ur}{r_{A}}\right) / J_{k}\left(u\right) & |r| \leq r_{A} \\ K_{k}\left(\frac{vr}{r_{A}}\right) / K_{k}\left(v\right) & |r| \geq r_{A} \end{cases}$$

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The standing optical wave of the fundamental mode



• The 980 nm VCSEL active layer contains a pair of three 70/80Å In_{0.2}Ga_{0.8}As/GaAs QWs/barriers, separated by the inter-barrier designed to place a QWs in a maxima of generated field

Electrical phenomena

Poisson equations

$$\nabla \cdot \boldsymbol{\varepsilon} \nabla V = -e\left(p - n + N_D^+ - N_A^-\right)$$

Current density of electrons and holes

 $j_{n} = -e\mu_{n}\nabla V + eD_{n}\nabla n + eD_{n}^{T}\nabla T$ $j_{p} = -e\mu_{p}\nabla V - eD_{p}\nabla p - eD_{p}^{T}\nabla T$

mobility diffusion thermal diffusion

Continuity equations for electrons and holes

$$\begin{aligned} &\frac{\partial n}{\partial t} = \frac{1}{e} \nabla \cdot j_n + (G - R), \\ &\frac{\partial p}{\partial t} = -\frac{1}{e} \nabla \cdot j_p + (G - R). \end{aligned}$$

Carrier generation rate

$$G = \frac{\left|j_{n}\right|}{eL_{z}} = \frac{\left|j_{p}\right|}{eL_{z}}$$

Carrier recombination rate

$$R = \underbrace{R_{sp} + R_{st}}_{radiative} + \underbrace{R_{SRH} + R_{A}}_{nonradiative}$$



Energy band distribution





Electron current magnitude for different pumping currents





Thermal phenomena Basic thermal equation Heat sources $C_{P}\rho \frac{\partial T}{\partial t} = \nabla \cdot \kappa \nabla T + H$ Material density Thermal conductivity Heat coefficient $H = H_{Joule-dc} + H_{Joule-op} + H_{rec} + H_T + H_P$



Steady-stateOptical wave absorptionRecombination ThomsonPeltier heatElectrical fieldon loss semiconductorsheatheat

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Power versus current







The modulation conversion efficiency factor





The solid lines present the fitting with modulation conversion efficiency factor of 159 and 240 GHz/(A)^{0.5} for device with one and two triplets of QWs, respectively

Conclusion



- we have analyzed the thermal, electrical, optical, and modulation properties of the 980 nm InGaAs ICOC VCSELs with different structures of active layer
- Results show inserting quantum wells in maxima of the generated field increases the slope efficiency of L-I characteristic due to increasing the modal gain of device
- The analysis of modulation characteristics clarify that devices with two triplets of QWs have wider modulation bandwidth and the modulation conversion efficiency factor is approximately 240 GHz/(A)^{0.5} due to more efficient position of QWs in the resonator.

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